



IPC-9691B

User Guide for the IPC-TM-650, Method 2.6.25, Conductive Anodic Filament (CAF) Resistance and Other Internal Electrochemical Migration Testing

Developed by the Electrochemical Migration Task Group (5-32e) of the Cleaning and Coating Committee (5-30) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC

Table of Contents

1	SCOPE	1	
2	BACKGROUND	1	
3	PURPOSE	1	
4	INTRODUCTION	1	
5	WHAT IS CONDUCTIVE ANODIC FILAMENT GROWTH?	3	
6	OTHER INTERNAL ECM MODES	4	
7	INCREASING INTERNAL ECM RISK TRENDS	5	
8	ADJUSTED CALCE CAF FAILURE MODEL	6	
9	INTERNAL ECM TEST VEHICLE DESIGN	7	
9.1	Printed Board Thickness and Stackup	7	
9.2	Via Patterns and Drill Parameters	8	
9.3	Solder Mask	8	
9.4	Surface Finish	12	
10	INTERNAL ECM TEST BOARD SAMPLE PREPARATION & TESTING	13	
11	INTERNAL ECM TEST DATA FORMAT	14	
12	INTERNAL ECM TEST SPACING DATA ANALYSIS	15	
13	SAMPLE SIZES	16	
14	RELATING CAF RESISTANCE TEST RESULTS TO EXPECTED FIELD LIFE	18	
15	SPECIFYING INTERNAL ECM RESISTANCE	18	
16	LOCATION OF TESTING	19	
17	LOCATING INTERNAL ECM FAILURES	20	
18	FACTORS AFFECTING INTERNAL ECM RESISTANCE	22	
19	CONCLUSIONS	26	
20	SUMMARY	27	
APPENDIX A	Other Internal ECM or CAF Resistance Test Boards/ Coupons	28	
Figures			
Figure 4-1	Example of an Internal Conductive Filament	1	
Figure 4-2	Two Perspectives of the Same Conductive Path	2	
Figure 4-3	Two Photos Showing Failure Between Plated Through Holes	2	
Figure 4-4	Failure Analysis Photo Showing Suspected CAF Failure Between Very Closely-Spaced Plated Through Holes	2	
Figure 6-1	Cross-section SEM micrograph of a laminate material. The hollow glass fibers are highlighted.	4	
Figure 6-2	A cross-section of a hollow fiber can be seen in the middle fiber in this SEM micrograph. Hollow fibers of smaller diameter may be potentially more damaging as they tend to fill faster with conductive medium.	4	
Figure 8-1	Typical Copper Wicking in a Plated Through Hole	6	
Figure 8-2a	Internal Separation	6	
Figure 8-2b	Damage Due to Hole Drilling and Wicking	6	
Figure 9-1	IPC-9253 Test Coupon Region A: Plated Through Holes in Alignment with X, Y	7	
Figure 9-2	Region B Via Test Pattern. The Anode Vias are Staggered Diagonally to the Cathode Vias	7	
Figure 9-3	The gap between solder mask and metal can create a channel that entraps contaminants, such as in this example of a product failure (not a CAF coupon).	9	
Figure 9-4	Potential solder mask anomalies on ECM coupons, which can cause surface defects unrelated to target ECM performance. LEFT: poor solder mask adhesion; RIGHT: broken solder mask webs.	9	
Figure 9-5	Some surface defects can be challenging to find, such as this small dendrite on an ECM coupon.	10	
Figure 9-6	Severe damage caused by heavy dendritic growth resulted in complete disqualification of test results from this ECM test coupon.	11	
Figure 9-7	LEFT: This image illustrates how plugged and covered vias are effective at eliminating corrosion, compared with adjacent, non-plugged vias. RIGHT: Cross section of ink-plugged via, covered with solder mask.	11	
Figure 9-8	LEFT: voiding and incomplete fill is typical with solder mask ink-plugged vias. RIGHT: via filling with epoxy resin is highly consistent and repeatable.	12	
Figure 13-1	TB38A as Manufactured by Board House with NiAu (ENIG) Finish	16	
Figure 13-2	Schematic of In-Line Test Comb, With Possible Failure Site	17	
Figure 13-3	Schematic Section of Via Pair With Bias Applied	17	

Figure 13-4	Schematic of Staggered Test Comb, With Possible Failure Site	17
Figure 13-5	Internal ECM Test Coupons Under Test in Environmental Chamber	17
Figure 15-1	Example of the Electrical Effect of a Typical CAF Failure	19
Figure 17-1	Schematic Section to Illustrate Polishing to Locate CAF	20
Figure 17-2	Schematic Section to Illustrate Polishing to Locate CAF	20
Figure 17-3	Hollow Fiber (filled with ECM Cu deposits)	21
Figure 17-4	Striation ("tri-point" from poor wetting of glass fiber bundle)	21
Figure 18-1	Effect of Via Wall-to-Wall Gap on TTF	22
Figure 18-2	Effect of Via Alignment on TTF, for 2113 and 2116 Glass-Reinforced Laminates	22
Figure 18-3	Effect of Surface Finish on TTF	23
Figure 18-4	Effect of Drill Feed Rate	23
Figure 18-5	Effect of Reflow	24
Figure 18-6	Effect of Board House	24
Figure 18-7	Effect of Material T_g	25
Figure 18-8	Effect of Reinforcement – Board House A, Drill 1, NiAu (ENIG) Finish	25
Figure 18-9	TTF Data for CAF and Non-CAF Resistant Laminate	26
Figure A-1	IBM CAF TV	29
Figure A-2	ALU MRT-6 CAF Test Vehicle	30

Figure A-3	ALU CAF-2 Test Vehicle	31
Figure A-4	Cisco Sipedon CAF Test Vehicle	32

Tables

Table 7-1	Plated Through Hole Wall-to-Wall Spacing Trends	5
Table 9-1	Typical Resin Content vs. Glass Fiber Content in Common Prepreg Glass Weave Styles	8
Table 11-1	Typical SIR-Type Resistance Data Reporting ..	14
Table 11-2	Same Data from Table 11-1, Sorted for Each CAF Analysis	15
Table 12-1	Typical Dicyandiamide-Cured FR-4 Laminate Test Results from SIR-Type Resistance Data	16
Table 18-1	Coupon Conditions Selected for Comparison of Surface Finishes	22
Table 18-2	Coupon Conditions Selected for Comparison of Drill Parameters	23
Table 18-3	Coupon Conditions Selected for Comparison of Reflow Conditions	24
Table 18-4	Coupon Conditions Selected for Comparison of Manufacturing Site	24
Table 18-5	Coupon Conditions Selected for Comparison of Material T_g	25
Table 18-6	Coupon Conditions Selected for Comparison of Reinforcements	25
Table 18-7	Coupon Conditions Selected for Comparison of CAF Designation	26

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1 SCOPE

This document is the product of the IPC Electrochemical Migration (ECM) Task Group. It was drafted to provide guidance regarding implementation of the User Guide for the IPC-TM-650, Method 2.6.25, Conductive Anodic Filament (CAF) Resistance and Other Internal Electrochemical Migration Testing to evaluate the effects of mechanical stress, laminate material fracturing, ionic contamination, moisture content prior to press lamination, and other material processing characteristics on formation of conductive paths within laminate material such as conductive anodic filaments (CAF), one specific type of ECM failure mode. This internal ECM test method provides a proven standard for determining the risk of through-hole bias and other internal conductor orientations that result in significant reduction of insulation resistance internally, rather than on the surface of printed boards.

2 BACKGROUND

In recent years, internal electrochemical migration (ECM) liability concerns in the industry have increased as board designs have advanced in terms of decreasing clearances, dimensions and/or higher voltages. ECM failures describe any phenomena that causes internal drop in insulation resistance, including conductive anodic filament (CAF) formation, weak polymer resin bond, hollow fibers, poor wetting of glass reinforcement fibers with resin, foreign material or contamination, rough hole walls, and excessive copper wicking within plated through holes. Temperature, humidity and bias testing of insulation resistance using test coupons is the methodology used to check for these defects. The user of this document is encouraged to become familiar with IPC-9201, *Surface Insulation Resistance Handbook* to distinguish between internal ECM failures and possible confounding Surface Insulation Resistance (SIR) failures.

3 PURPOSE

This user guide addresses test issues regarding determining pass/fail criteria based on knowledge of three product goals:

- a) What are the long term reliability requirements?
- b) What is the closest spacing required for a given voltage?
- c) Evaluate the internal ECM Failure risk.

4 INTRODUCTION

Internal ECM, including conductive filament growth occurs within a printed board and may or may not be visible under a microscope. It is often associated with adjacent laminate material fracturing or defect (i.e., “pathway”) that contributed to its formation. Examples of visible filament growth shown in Figures 4-1, 4-2, 4-3 and 4-4 would fail the temperature, humidity, and bias conditions selected to determine multilayer board reliability between internal features.

The high magnification photo, Figure 4-1 below, shows a printed board with layer 1 (top layer) removed, revealing a near shorting condition between the plated through hole and layer 2 ground plane.

Poor press lamination and/or defective prepreg material may contribute to entrapped contaminants and the formation of conductive pathways which results in early test failure if the resin/reinforcement bonding strength and resistance to mechanical stress is reduced.

Failure analysis, as seen in two perspectives in Figure 4-2, show a near-shorting condition from the hole barrel to the plane on layer 3.

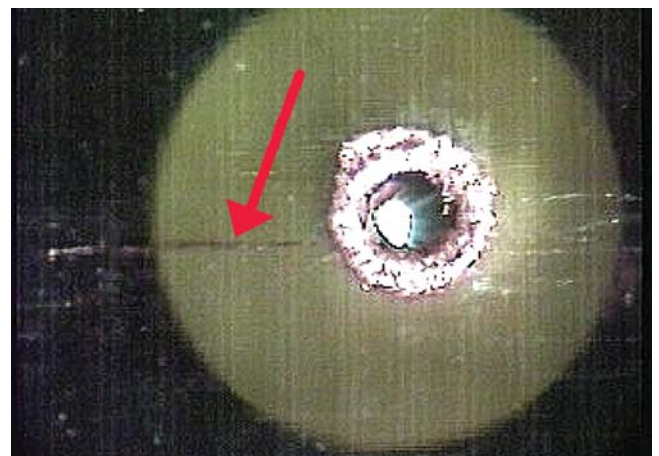


Figure 4-1 Example of an Internal Conductive Filament
[Photo courtesy of Matsushita]